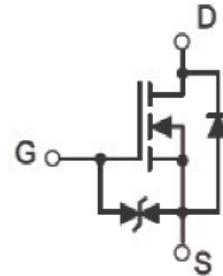


»Features

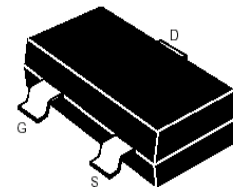
$V_{DS} = 60V$
 $I_D = 0.2A$
 $R_{DS(ON)} @V_{GS} = 10V, \text{ Max } = 3\Omega$
 $R_{DS(ON)} @V_{GS} = 4.5V, \text{ Max } = 4\Omega$

»Pin Configurations



»General Description

- Super High dense cell design for extremely low RDS(ON)
- Reliable and Rugged.
- SOT-323 for Surface Mount Package.
- ESD protected



SOT-323

»Absolute Maximum Ratings @ $T_A=25^\circ C$ unless otherwise noted

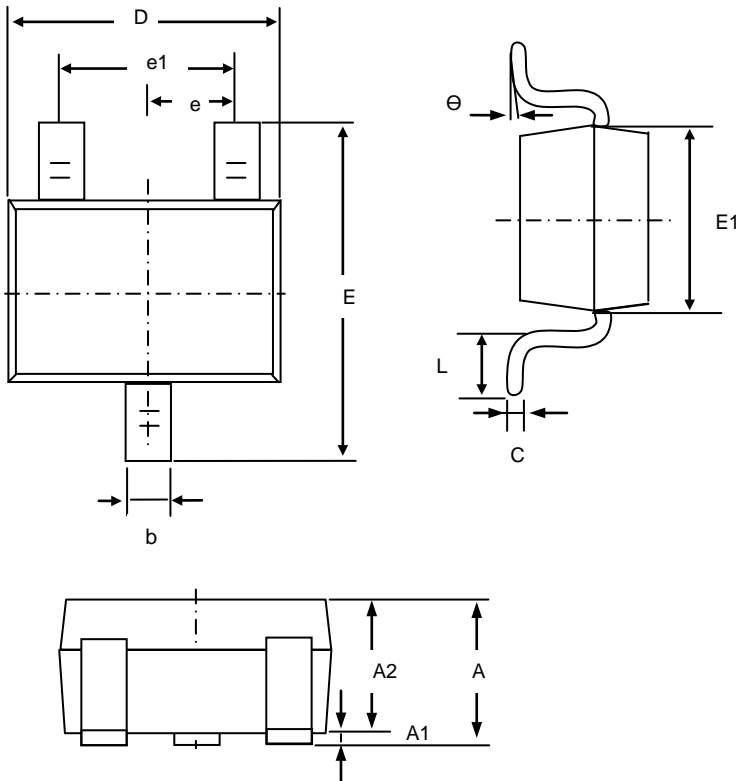
Parameter	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	0.2	A
Power Dissipation	P_D	0.225	W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	556	$^\circ C/W$
Junction Temperature	T_J	150	$^\circ C$
Storage Temperature	T_{stg}	-50~+150	

»Electrical Characteristics @ $T_A=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static Characteristics						
BVDSS	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_{DS} = 250\ \mu\text{ A}$	60	-	-	V
VGS(th)	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{DS} = 250\ \mu\text{ A}$	0.8	1.5	2.5	V
IDSS	Drain Leakage Current	$V_{DS} = 48\text{ V}, V_{GS} = 0\text{ V}$	-	-	1	$\mu\text{ A}$
		$T_J = 85\ ^{\circ}\text{C}$	-	-	30	$\mu\text{ A}$
IGSS	Gate Leakage Current	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$	-	-	± 10	$\mu\text{ A}$
RDS(ON) ^a	On-State Resistance	$V_{GS} = 10\text{ V}, I_{DS} = 0.5\text{ A}$	-	1.9	3	Ω
		$V_{GS} = 4.5\text{ V}, I_{DS} = 0.2\text{ A}$	-	2.4	4	
Diode Characteristics						
VSD	Diode Forward Voltage	$I_{SD} = 0.5\text{ A}, V_{GS} = 0\text{ V}$	-	0.7	1.3	V

»Package Information

SOT-323



Symbol	Dim in mm		
	Min	Nor	Max
A	0.90	1.00	1.10
A1	0.00	0.05	0.10
A2	0.90	0.95	1.00
b	0.20	0.30	0.40
c	0.08	0.12	0.15
D	2.00	2.10	2.20
E	2.15	2.30	2.45
E1	1.15	1.25	1.35
e	0.650TPY.		
e1	1.2	1.3	1.4
L	0.26	0.36	0.46
θ	0°	4°	8°

»Ordering information

Order code	Package	Marking	Base qty	Delivery mode
2N7002KW	SOT-323	72K	3K	Tape and reel